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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	CSIO, EBI/EMI, I²C, LINbus, SPI, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	83
Program Memory Size	384KB (384K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 16x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy9af115napmc-g-mne2

Watch dog Timer (2 channels)

A watchdog timer can generate interrupts or a reset when a time-out value is reached.

This series consists of two different watchdogs, a "Hardware" watchdog and a "Software" watchdog.

The "Hardware" watchdog timer is clocked by the built-in low-speed CR oscillator. Therefore, the "Hardware" watchdog is active in any low-power consumption modes except STOP modes.

External Interrupt Controller Unit

- Up to 16 external interrupt input pins
- Include one non-maskable interrupt (NMI) input pin

General-Purpose I/O Port

This series can use its pins as general-purpose I/O ports when they are not used for external bus or peripherals. Moreover, the port relocate function is built in. It can set which I/O port the peripheral function can be allocated to.

- Capable of pull-up control per pin
- Capable of reading pin level directly
- Built-in the port relocate function
- Up to 83 fast General Purpose I/O Ports@ 100pin Package
- Some ports are 5V tolerant I/O (MB9AF115MA/NA, MB9AF116MA/NA only)
  Please see "Pin Description" to confirm the corresponding pins.

CRC (Cyclic Redundancy Check) Accelerator

The CRC accelerator calculates the CRC which has a heavy software processing load, and achieves a reduction of the integrity check processing load for reception data and storage.

CCITT CRC16 and IEEE-802.3 CRC32 are supported.

- CCITT CRC16 Generator Polynomial: 0x1021
- IEEE-802.3 CRC32 Generator Polynomial: 0x04C11DB7

Clock and Reset

[Clocks]

Selectable from five clock sources (2 external oscillators, 2 built-in CR oscillators, and Main PLL).

- Main Clock : 4 MHz to 48 MHz
- Sub Clock : 32.768 kHz
- Built-in High-speed CR Clock : 4 MHz
- Built-in Low-speed CR Clock : 100 kHz
- Main PLL Clock

[Resets]

- Reset requests from INITX pin
- Power-on reset
- Software reset
- Watchdog timers reset
- Low-voltage detector reset
- Clock Supervisor reset

Clock Super Visor (CSV)

Clocks generated by built-in CR oscillators are used to supervise abnormality of the external clocks.

- External clock failure (clock stop) is detected, reset is asserted.
- External frequency anomaly is detected, interrupt or reset is asserted.

Low-Voltage Detector (LVD)

This Series includes 2-stage monitoring of voltage on the VCC. When the voltage falls below the voltage that has been set, Low-Voltage Detector generates an interrupt or reset.

- LVD1: error reporting via interrupt
- LVD2: auto-reset operation

Low-Power Consumption Mode

Three Low-Power Consumption modes supported.

- SLEEP
- TIMER
- STOP

Debug

- Serial Wire JTAG Debug Port (SWJ-DP)
- Embedded Trace Macrocells (ETM)*
  *: Mb9AF111LA/MA, F112LA/MA, F114LA/MA, F115MA and F116MA support only SWJ-DP.

Power Supply

- VCC = 2.7V to 5.5V: Correspond to the wide range voltage.

Contents

Pin No					Pin name	I/O circuit type	Pin state type
LQFP-100	QFP-100	BGA-112	LQFP-80	LQFP-64 QFN-64			
14	92	F2	-	-	P35 IC03_0 TIOB5_1 INT08_1 MADATA12_1	E	H
15	93	F3	-	-	P36 IC02_0 SIN5_2 INT09_1 MADATA13_1	E	H
16	94	G1	-	-	P37 IC01_0 SOT5_2 (SDA5_2) INT10_1 MADATA14_1	E	H
17	95	G2	-	-	P38 IC00_0 SCK5_2 (SCL5_2) INT11_1 MADATA15_1	E	H
18	96	F4	13	9	P39 DTTI0X_0 ADTG_2	E	I
19	97	G3	14	10	P3A RTO00_0 (PPG00_0) TIOA0_1	G	I
20	98	H1	15	11	P3B RTO01_0 (PPG00_0) TIOA1_1	G	I
21	99	H2	16	12	P3C RTO02_0 (PPG02_0) TIOA2_1	G	I
22	100	G4	17	13	P3D RTO03_0 (PPG02_0) TIOA3_1	G	I
-	-	B2	-	-	VSS	-	

Pin No					Pin name	I/O circuit type	Pin state type
LQFP-100	QFP-100	BGA-112	LQFP-80	LQFP-64 QFN-64			
71	49	D10	57	46	P23	E	I
					SCK0_0 (SCL0_0)		
					TIOA7_1		
			-	-	RTO00_1 (PPG00_1)		
72	50	E8	58	47	P22	E	I
					SOT0_0 (SDA0_0)		
					TIOB7_1		
				-	ZIN1_1		
73	51	C11	59	48	P21	E	H
					SIN0_0		
					INT06_1		
				-	BIN1_1		
74	52	C10	60	-	P20	E	H
					INT05_0		
					CROUT_0		
					AIN1_1		
					MAD24_1		
75	53	A11	-	-	VSS	-	
76	54	A10	-	-	VCC	-	
77	55	A9	61	49	P00	E	E
					TRSTX		
				-	MCSX7_1		
78	56	B9	62	50	P01	E	E
					TCK		
					SWCLK		
79	57	B11	63	51	P02	E	E
					TDI		
				-	MCSX6_1		
80	58	A8	64	52	P03	E	E
					TMS		
					SWDIO		
81	59	B8	65	53	P04	E	E
					TDO		
					SWO		
82	60	C8	-	-	P05	E	F
					TRACED0		
					TIOA5_2		
					SIN4_2		
					INT00_1		
					MCSX5_1		
-	-	D8	-	-	VSS	-	

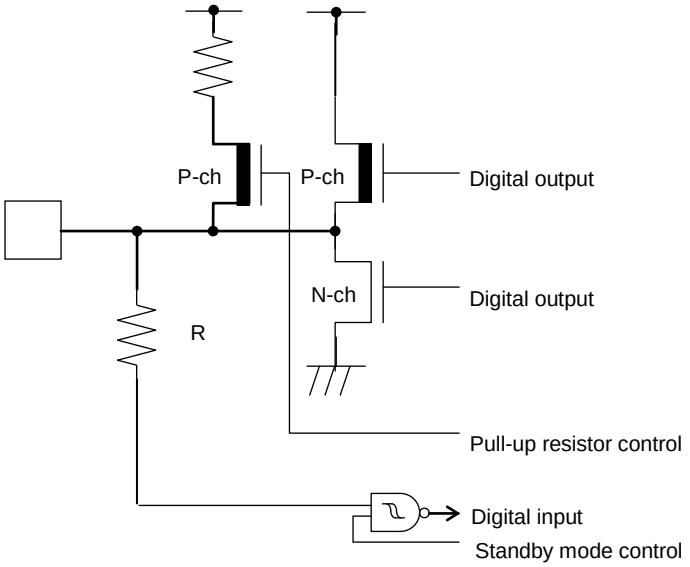
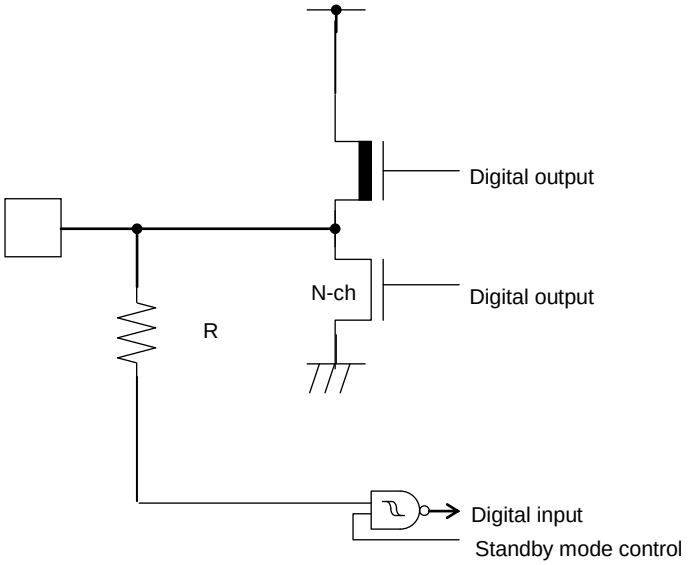
Pin No					Pin name	I/O circuit type	Pin state type
LQFP-100	QFP-100	BGA-112	LQFP-80	LQFP-64 QFN-64			
83	61	D9	-	-	P06 TRACED1 TIOB5_2 SOT4_2 (SDA4_2) INT01_1 MCSX4_1	E	F
84	62	A7	66 -	-	P07 ADTG_0 MCLKOUT_1 TRACED2 SCK4_2 (SCL4_2)	E	G
85	63	B7	-	-	P08 TRACED3 TIOA0_2 CTS4_2 MCSX3_1	E	G
86	64	C7	-	-	P09 TRACECLK TIOB0_2 RTS4_2 MCSX2_1	E	G
87	65	D7	67	54 -	P0A SIN4_0 INT00_2 FRCK1_0 MCSX1_1	E / I*	H
88	66	A6	68	55 -	P0B SOT4_0 (SDA4_0) TIOB6_1 IC10_0 MCSX0_1	E / I*	I
89	67	B6	69	56 -	P0C SCK4_0 (SCL4_0) TIOA6_1 IC11_0 MALE_1	E / I*	I
-	-	D4	-	-	VSS	-	
-	-	C3	-	-	VSS	-	

Module	Pin name	Function	Pin No				
			LQFP-100	QFP-100	BGA-112	LQFP-80	LQFP-64 QFN-64
External Interrupt	INT00_0	External interrupt request 00 input pin	2	80	C1	2	2
	INT00_1		82	60	C8	-	-
	INT00_2		87	65	D7	67	54
	INT01_0	External interrupt request 01 input pin	3	81	C2	3	3
	INT01_1		83	61	D9	-	-
	INT02_0	External interrupt request 02 input pin	4	82	B3	4	4
	INT02_1		53	31	J10	43	35
	INT03_0	External interrupt request 03 input pin	93	71	D6	73	-
	INT03_1		56	34	H9	46	38
	INT03_2		9	87	E1	9	5
	INT04_0	External interrupt request 04 input pin	12	90	E4	12	8
	INT04_1		59	37	G9	49	40
	INT04_2		10	88	E2	10	6
	INT05_0	External interrupt request 05 input pin	74	52	C10	60	-
	INT05_1		65	43	F9	55	-
	INT05_2		11	89	E3	11	7
	INT06_1	External interrupt request 06 input pin	73	51	C11	59	48
	INT06_2		45	23	K8	35	27
	INT07_2	External interrupt request 07 input pin	5	83	D1	5	-
	INT08_1	External interrupt request 08 input pin	14	92	F2	-	-
	INT08_2		8	86	D5	8	-
	INT09_1	External interrupt request 09 input pin	15	93	F3	-	-
	INT10_1	External interrupt request 10 input pin	16	94	G1	-	-
	INT11_1	External interrupt request 11 input pin	17	95	G2	-	-
	INT12_1	External interrupt request 12 input pin	27	5	J4	-	-
	INT13_1	External interrupt request 13 input pin	28	6	L5	-	-
	INT14_1	External interrupt request 14 input pin	39	17	K6	29	-
	INT15_1	External interrupt request 15 input pin	96	74	C4	76	60
	NMIX	Non-Maskable Interrupt input	92	70	B5	72	57

Module	Pin name	Function	Pin No				
			LQFP-100	QFP-100	BGA-112	LQFP-80	LQFP-64 QFN-64
Reset	INITX	External Reset Input. A reset is valid when INITX="L"	38	16	K4	28	21
Mode	MD0	Mode 0 pin. During normal operation, MD0="L" must be input. During serial programming to flash memory, MD0="H" must be input.	47	25	L8	37	29
	MD1	Mode 1 pin. During serial programming to flash memory, MD1="L" must be input.	46	24	K9	36	28
Power	VCC	Power supply pin	1	79	B1	1	1
	VCC	Power supply pin	26	4	J1	-	-
	VCC	Power supply pin	35	13	K1	25	18
	VCC	Power supply pin	51	29	K11	41	33
	VCC	Power supply pin	76	54	A10	-	-
	VCC	Power supply pin	97	75	A4	77	61
GND	VSS	GND pin	-	-	B2	-	-
	VSS	GND pin	25	3	L1	20	16
	VSS	GND pin	-	-	K2	-	-
	VSS	GND pin	-	-	J3	-	-
	VSS	GND pin	-	-	H4	-	-
	VSS	GND pin	34	12	L4	24	-
	VSS	GND pin	50	28	L11	40	32
	VSS	GND pin	-	-	K10	-	-
	VSS	GND pin	-	-	J9	-	-
	VSS	GND pin	-	-	H8	-	-
	VSS	GND pin	-	-	B10	-	-
	VSS	GND pin	-	-	C9	-	-
	VSS	GND pin	75	53	A11	-	-
	VSS	GND pin	-	-	D8	-	-
	VSS	GND pin	-	-	D4	-	-
	VSS	GND pin	-	-	C3	-	-
	VSS	GND pin	100	78	A1	80	64
Clock	X0	Main clock (oscillation) input pin	48	26	L9	38	30
	X0A	Sub clock (oscillation) input pin	36	14	L3	26	19
	X1	Main clock (oscillation) I/O pin	49	27	L10	39	31
	X1A	Sub clock (oscillation) I/O pin	37	15	K3	27	20
	CROUT_0	Built-in high-speed CR-osc clock output port	74	52	C10	60	-
	CROUT_1		92	70	B5	72	57
Analog Power	AVCC	A/D converter analog power supply pin	60	38	H11	50	41
	AVRH	A/D converter analog reference voltage input pin	61	39	F11	51	42
Analog GND	AVSS	A/D converter GND pin	62	40	G11	52	43
C pin	C	Power supply stabilization capacity pin	33	11	L2	23	17

Note:

- While this device contains a Test Access Port (TAP) based on the IEEE 1149.1-2001 JTAG standard, it is not fully compliant to all requirements of that standard. This device may contain a 32-bit device ID that is the same as the 32-bit device ID in other devices with different functionality. The TAP pins may also be configurable for purposes other than access to the TAP controller.

Type	Circuit	Remarks
G		• CMOS level output • CMOS level hysteresis input • With pull-up resistor control • With standby mode control • Pull-up resistor : Approximately 50kΩ • I_{OH}=-12mA, I_{OL}= 12mA • +B input is available
H		• CMOS level output • CMOS level hysteresis input • With standby mode control • I_{OH} = -20.5mA, I_{OL} = 18.5mA

6. Handling Precautions

Any semiconductor devices have inherently a certain rate of failure. The possibility of failure is greatly affected by the conditions in which they are used (circuit conditions, environmental conditions, etc.). This page describes precautions that must be observed to minimize the chance of failure and to obtain higher reliability from your Cypress semiconductor devices.

6.1 Precautions for Product Design

This section describes precautions when designing electronic equipment using semiconductor devices.

Absolute Maximum Ratings

Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of certain established limits, called absolute maximum ratings. Do not exceed these ratings.

Recommended Operating Conditions

Recommended operating conditions are normal operating ranges for the semiconductor device. All the device's electrical characteristics are warranted when operated within these ranges.

Always use semiconductor devices within the recommended operating conditions. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the datasheet. Users considering application outside the listed conditions are advised to contact their sales representative beforehand.

Processing and Protection of Pins

These precautions must be followed when handling the pins which connect semiconductor devices to power supply and input/output functions.

1. Preventing Over-Voltage and Over-Current Conditions

   Exposure to voltage or current levels in excess of maximum ratings at any pin is likely to cause deterioration within the device, and in extreme cases leads to permanent damage of the device. Try to prevent such overvoltage or over-current conditions at the design stage.
2. Protection of Output Pins

   Shorting of output pins to supply pins or other output pins, or connection to large capacitance can cause large current flows. Such conditions if present for extended periods of time can damage the device.
   Therefore, avoid this type of connection.
3. Handling of Unused Input Pins

   Unconnected input pins with very high impedance levels can adversely affect stability of operation. Such pins should be connected through an appropriate resistance to a power supply pin or ground pin.

Latch-up

Semiconductor devices are constructed by the formation of P-type and N-type areas on a substrate. When subjected to abnormally high voltages, internal parasitic PNPN junctions (called thyristor structures) may be formed, causing large current levels in excess of several hundred mA to flow continuously at the power supply pin. This condition is called latch-up.

CAUTION: The occurrence of latch-up not only causes loss of reliability in the semiconductor device, but can cause injury or damage from high heat, smoke or flame. To prevent this from happening, do the following:

1. Be sure that voltages applied to pins do not exceed the absolute maximum ratings. This should include attention to abnormal noise, surge levels, etc.
2. Be sure that abnormal current flows do not occur during the power-on sequence.

Observance of Safety Regulations and Standards

Most countries in the world have established standards and regulations regarding safety, protection from electromagnetic interference, etc. Customers are requested to observe applicable regulations and standards in the design of products.

Fail-Safe Design

Any semiconductor devices have inherently a certain rate of failure. You must protect against injury, damage or loss from such failures by incorporating safety design measures into your facility and equipment such as redundancy, fire protection, and prevention of over-current levels and other abnormal operating conditions.

Baking

Packages that have absorbed moisture may be de-moisturized by baking (heat drying). Follow the Cypress recommended conditions for baking.

Condition: 125°C/24 h

Static Electricity

Because semiconductor devices are particularly susceptible to damage by static electricity, you must take the following precautions:

1. Maintain relative humidity in the working environment between 40% and 70%. Use of an apparatus for ion generation may be needed to remove electricity.
2. Electrically ground all conveyors, solder vessels, soldering irons and peripheral equipment.
3. Eliminate static body electricity by the use of rings or bracelets connected to ground through high resistance (on the level of 1 MΩ).
   Wearing of conductive clothing and shoes, use of conductive floor mats and other measures to minimize shock loads is recommended.
4. Ground all fixtures and instruments, or protect with anti-static measures.
5. Avoid the use of styrofoam or other highly static-prone materials for storage of completed board assemblies.

6.3 Precautions for Use Environment

Reliability of semiconductor devices depends on ambient temperature and other conditions as described above.

For reliable performance, do the following:

1. Humidity

   Prolonged use in high humidity can lead to leakage in devices as well as printed circuit boards. If high humidity levels are anticipated, consider anti-humidity processing.
2. Discharge of Static Electricity

   When high-voltage charges exist close to semiconductor devices, discharges can cause abnormal operation. In such cases, use anti-static measures or processing to prevent discharges.
3. Corrosive Gases, Dust, or Oil

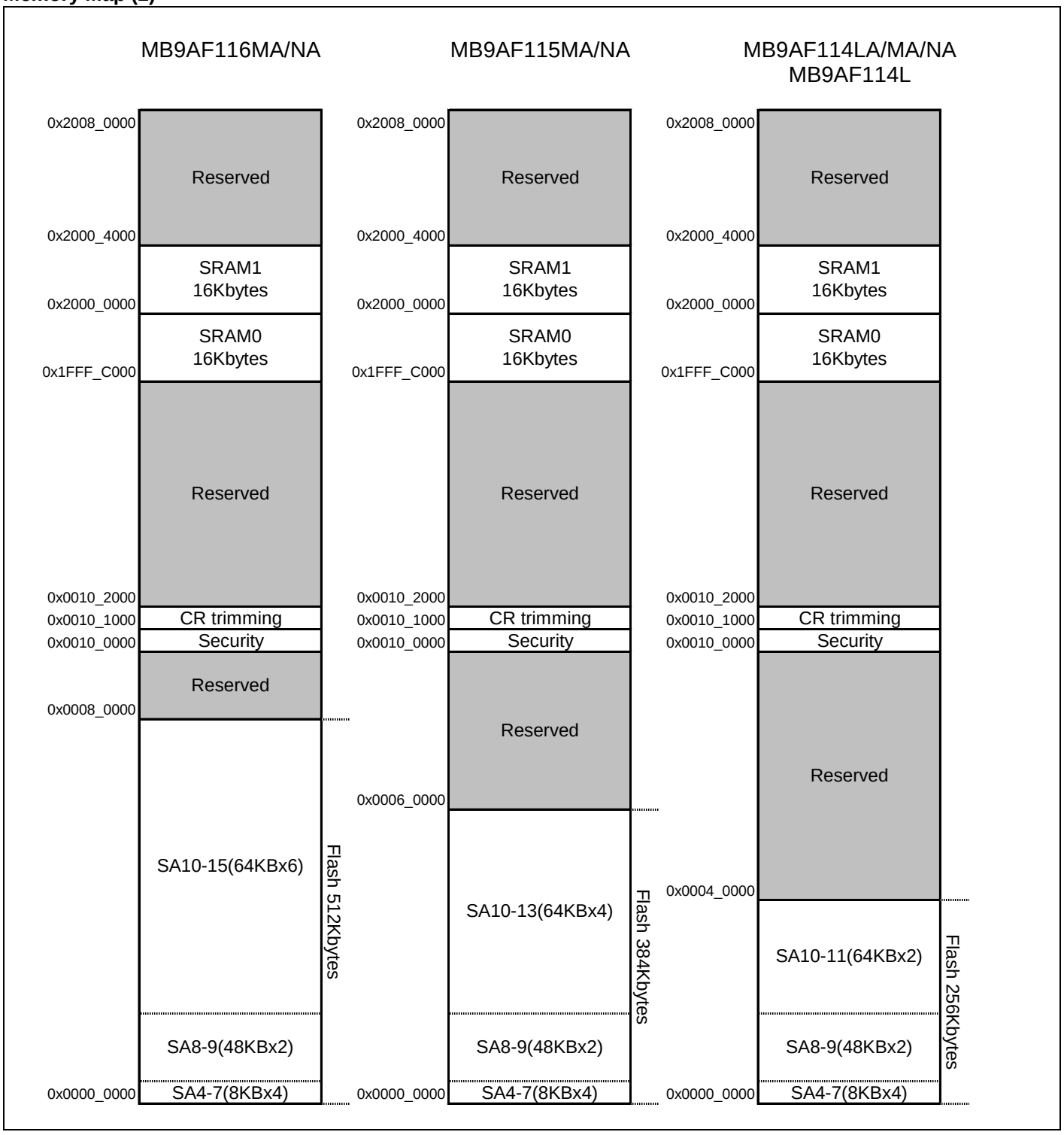
   Exposure to corrosive gases or contact with dust or oil may lead to chemical reactions that will adversely affect the device. If you use devices in such conditions, consider ways to prevent such exposure or to protect the devices.
4. Radiation, Including Cosmic Radiation

   Most devices are not designed for environments involving exposure to radiation or cosmic radiation. Users should provide shielding as appropriate.
5. Smoke, Flame

   CAUTION: Plastic molded devices are flammable, and therefore should not be used near combustible substances. If devices begin to smoke or burn, there is danger of the release of toxic gases.

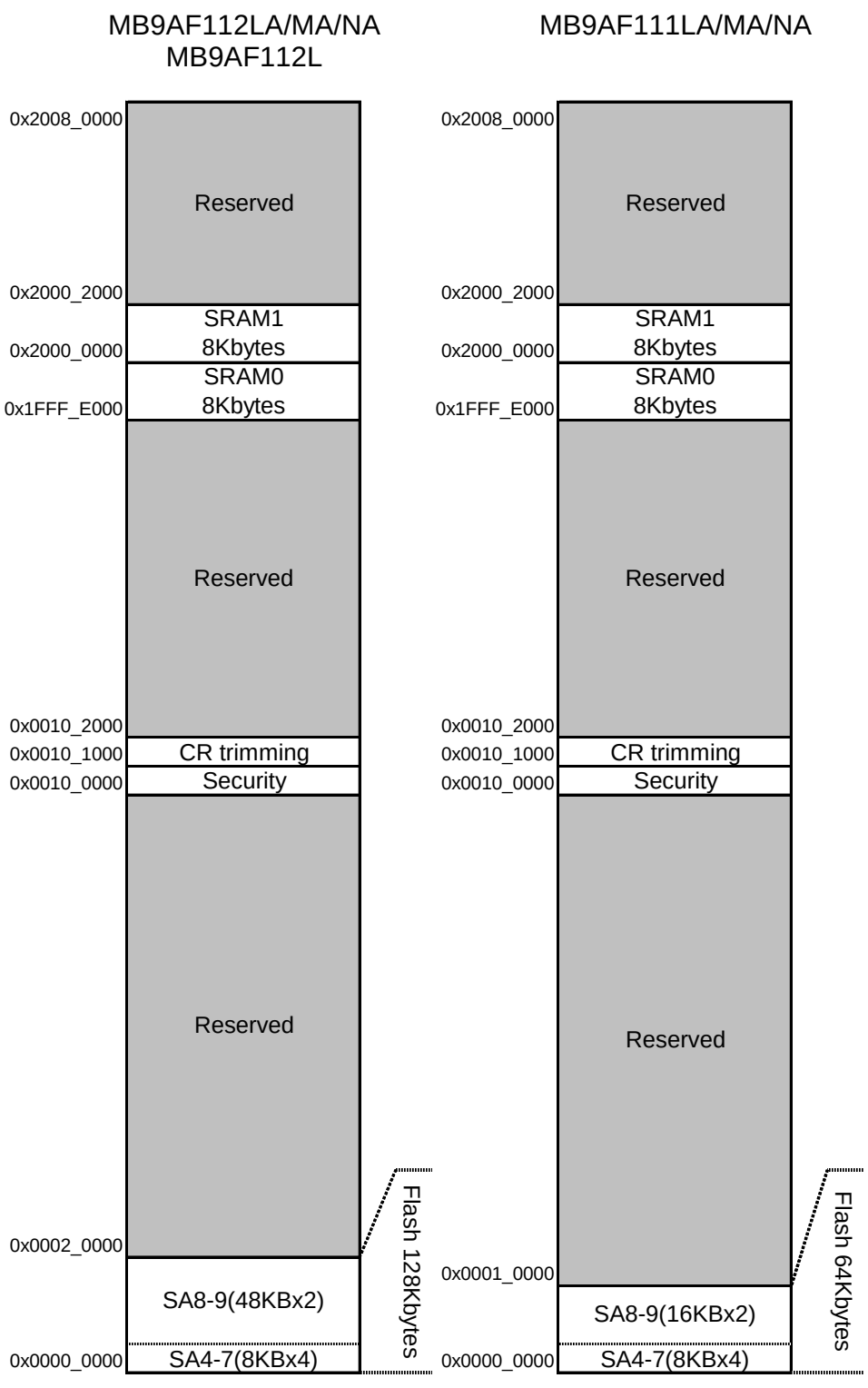
Customers considering the use of Cypress products in other special environmental conditions should consult with sales representatives.

Memory Map (2)



*: See "MB9A310A/110A Series Flash programming Manual" for sector structure of Flash.

Memory Map (3)



*: See "MB9A310A/110A Series Flash programming Manual" for sector structure of Flash.

Pin status type	Function group	Power-on reset or low-voltage detection state	INITX input state	Device internal reset state	Run mode or SLEEP mode state	Timer mode or STOP mode state	
		Power supply unstable	Power supply stable		Power supply stable	Power supply stable	
		-	INITX=0	INITX=1	INITX=1	INITX=1	
		-	-	-	-	SPL=0	SPL=1
M	GPIO selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z/ Internal input fixed at "0"
	Sub crystal oscillator input pin	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled
N	GPIO selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z/ Internal input fixed at "0"
	Sub crystal oscillator output pin	Hi-Z/ Internal input fixed at "0"/ or Input enabled	Hi-Z/ Internal input fixed at "0"	Hi-Z/ Internal input fixed at "0"	Maintain previous state	Maintain previous state/ Hi-Z at oscillation stop*2/ Internal input fixed at "0"	Maintain previous state/ Hi-Z at oscillation stop*2/ Internal input fixed at "0"
O	GPIO pin	Hi-Z	Hi-Z/ Input enabled	Hi-Z/ Input enabled	Maintain previous state	Maintain previous state	Hi-Z/ Internal input fixed at "0"
P	Mode input pin	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled
	GPIO selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z/Input enabled

*1: Oscillation is stopped at sub timer mode, low-speed CR timer mode, and stop mode.

*2: Oscillation is stopped at stop mode.

12.2 Recommended Operating Conditions

(V_{SS} = AV_{SS} = 0.0V)

Parameter		Symbol	Conditions	Value		Unit	Remarks
				Min	Max		
Power supply voltage		V_{CC}	-	2.7*2	5.5	V	
Analog power supply voltage		AV_{CC}	-	2.7	5.5	V	AV_{CC} = V_{CC}
Analog reference voltage		AVRH	-	2.7	AV_{CC}	V	
Smoothing capacitor		C_S	-	1	10	µF	For built-in regulator*1
Operating temperature	LQI100 LQH080 LQD064 LQG064 VNC064 LBC112	T_A	-	- 40	+ 105	°C	
	PQH100	T_A	When mounted on four-layer PCB	- 40	+ 105	°C	
			When mounted on double-sided single-layer PCB	- 40	+ 105	°C	I_{CC} ≤ 35mA
				- 40	+ 85	°C	I_{CC} > 35mA

*1: See " C Pin" in "7. Handling Devices" for the connection of the smoothing capacitor.

*2:In between less than the minimum power supply voltage and low voltage reset/interrupt detection voltage or more, instruction execution and low voltage detection function by built-in High-speed CR(including Main PLL is used) or built-in Low-speed CR is possible to operate only.

WARNING:

The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.
Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure. No warranty is made with respect to uses, operating conditions, or combinations not represented on the datasheet. Users considering application outside the listed conditions are advised to contact their representatives beforehand.

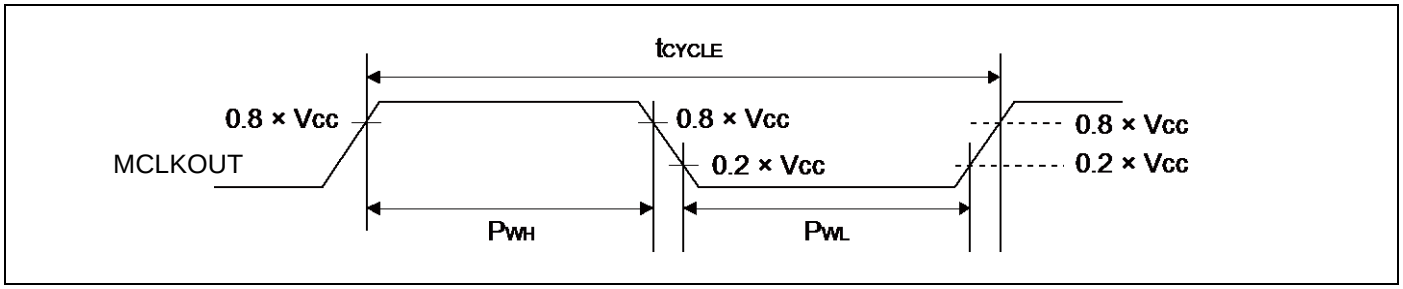
12.4.8 External Bus Timing

External bus clock output characteristics

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V, T_A = - 40°C to + 105°C)

Parameter	Symbol	Pin name	Conditions	Value		Unit
				Min	Max	
Output frequency	t_{CYCLE}	MCLKOUT	$V_{CC} \geq 4.5$ V	-	40	MHz
			$V_{CC} < 4.5$ V	-	32	MHz
Minimum clock cycle time	-		$V_{CC} \geq 4.5$ V	25	-	ns
			$V_{CC} < 4.5$ V	31.25	-	ns

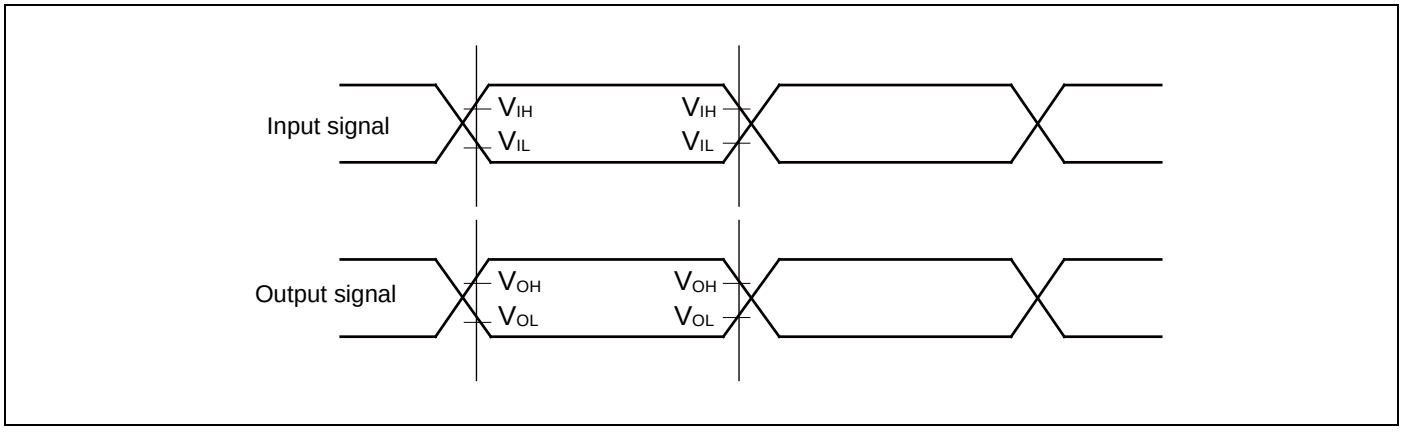
Note: The external bus clock output is a divided clock of HCLK. For more information about setting of clock divider, see "Chapter 12: External Bus Interface" in "FM3 Family Peripheral Manual"
When external bus clock is not output, this characteristic does not give any effect on external bus operation.



External bus signal input/output characteristics

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V, T_A = - 40°C to + 105°C)

Parameter	Symbol	Conditions	Value	Unit	Remarks
Signal input characteristics	V_{IH}	-	0.8 × V_{CC}	V	
	V_{IL}		0.2 × V_{CC}	V	
Signal output characteristics	V_{OH}		0.8 × V_{CC}	V	
	V_{OL}		0.2 × V_{CC}	V	

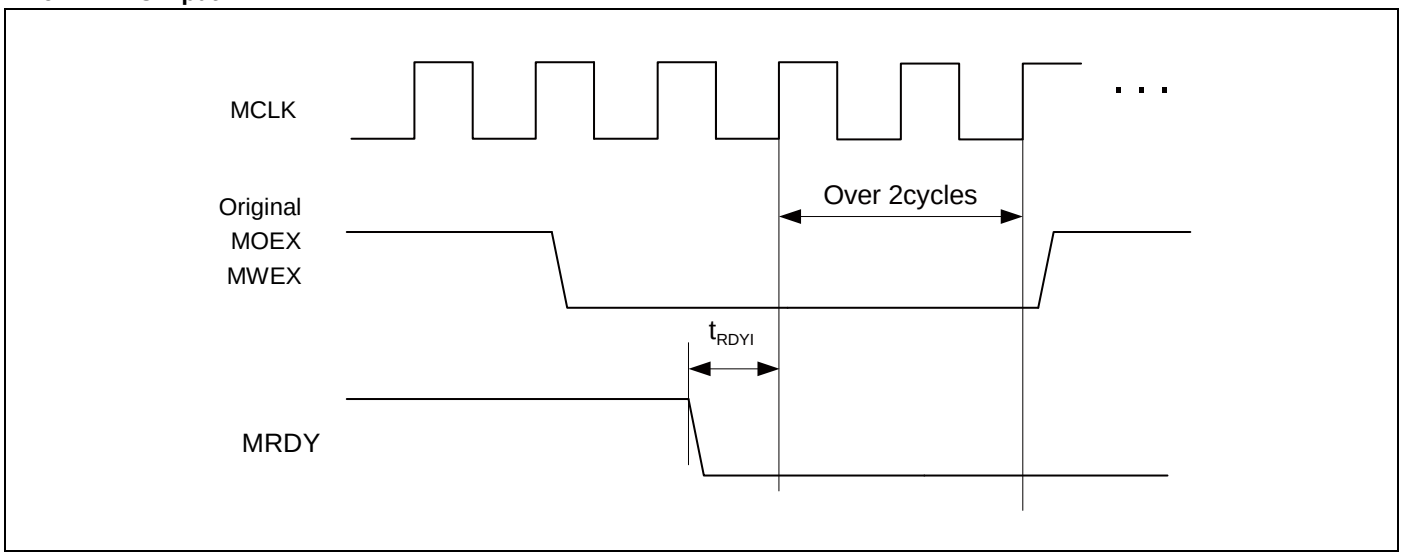


External Ready Input Timing

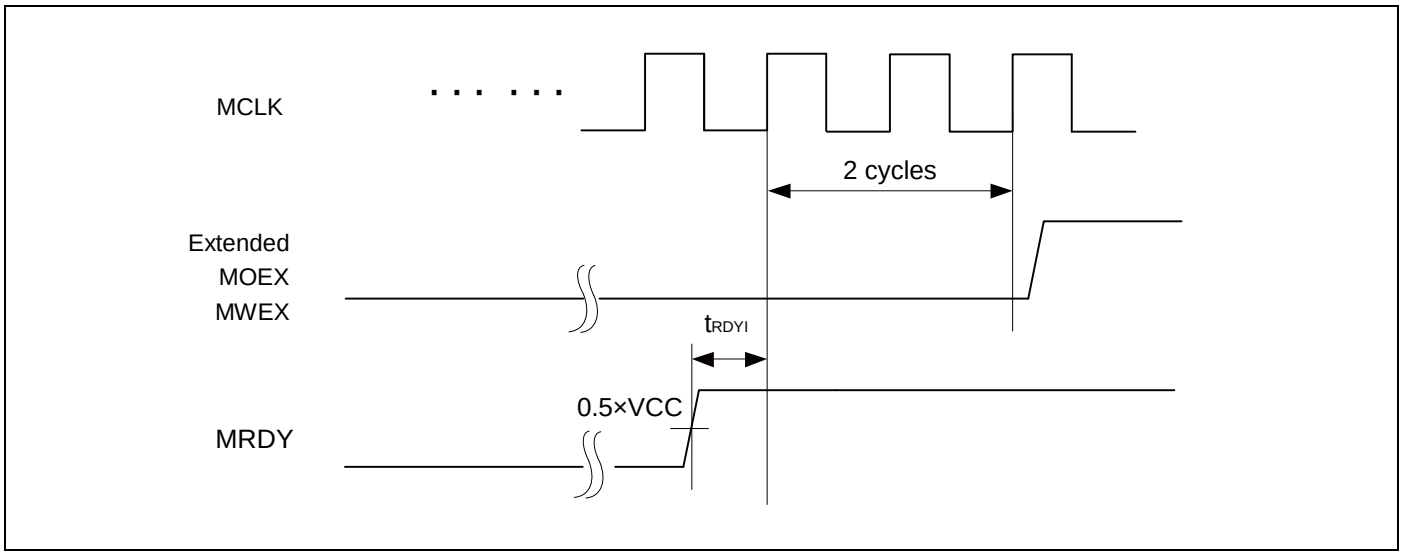
(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V, T_A = - 40°C to + 105°C)

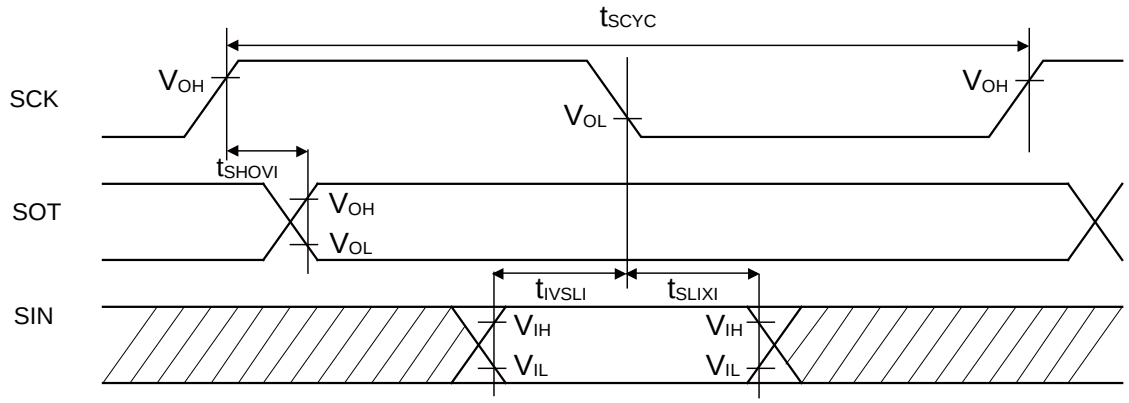
Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Min	Max		
MCLK ↑ MRDY input setup time	t_{RDYI}	MCLK MRDY	$V_{CC} \geq 4.5V$	19	-	ns	
			$V_{CC} < 4.5V$	37			

When RDY is input

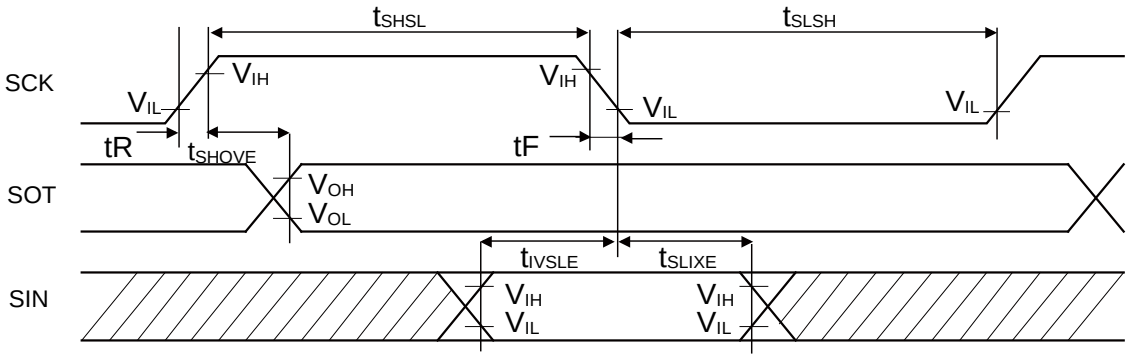


When RDY is released





Master mode



Slave mode

CSIO (SPI = 1, SCINV = 1)

(V_{CC} = 2.7V to 5.5V, V_{SS}= 0V, T_A = - 40°C to + 105°C)

Parameter	Symbol	Pin name	Conditions	V_{CC}<4.5V		V_{CC} ≥ 4.5V		Unit
				Min	Max	Min	Max	
Serial clock cycle time	t_{SCYC}	SCKx	Master mode	4tcycp	-	4tcycp	-	ns
SCK ↓⟶ SOT delay time	t_{SLOVI}	SCKx SOTx		- 30	+ 30	- 20	+ 20	ns
SIN ⟶ SCK ↑ setup time	t_{IVSHI}	SCKx SINx		50	-	30	-	ns
SCK ↑⟶SIN hold time	t_{SHIXI}	SCKx SINx		0	-	0	-	ns
SOT ⟶ SCK ↑ delay time	t_{SOVHI}	SCKx SOTx		2tcycp - 30	-	2tcycp - 30	-	ns
Serial clock "L" pulse width	t_{SLSH}	SCKx	Slave mode	2tcycp - 10	-	2tcycp - 10	-	ns
Serial clock "H" pulse width	t_{SHSL}	SCKx		tcycp + 10	-	tcycp + 10	-	ns
SCK ↓ ⟶ SOT delay time	t_{SLOVE}	SCKx SOTx		-	50	-	30	ns
SIN ⟶ SCK ↑ setup time	t_{IVSHE}	SCKx SINx		10	-	10	-	ns
SCK ↑⟶ SIN hold time	t_{SHIXE}	SCKx SINx		20	-	20	-	ns
SCK falling time	tF	SCKx		-	5	-	5	ns
SCK rising time	tR	SCKx		-	5	-	5	ns

Notes:

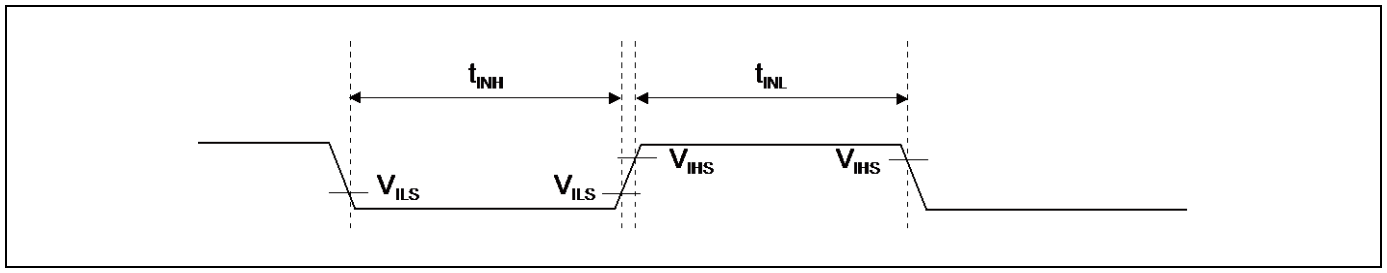
- The above characteristics apply to CLK synchronous mode.
- t_{CYCP} indicates the APB bus clock cycle time.
  About the APB bus number which Multi-function serial is connected to, see “8. Block Diagram” in this datasheet.
- These characteristics only guarantee the same relocate port number.
  For example, the combination of SCKx_0 and SOTx_1 is not guaranteed.
- When the external load capacitance C_L= 30pF.

12.4.11 External Input Timing

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V, T_A = - 40°C to + 105°C)

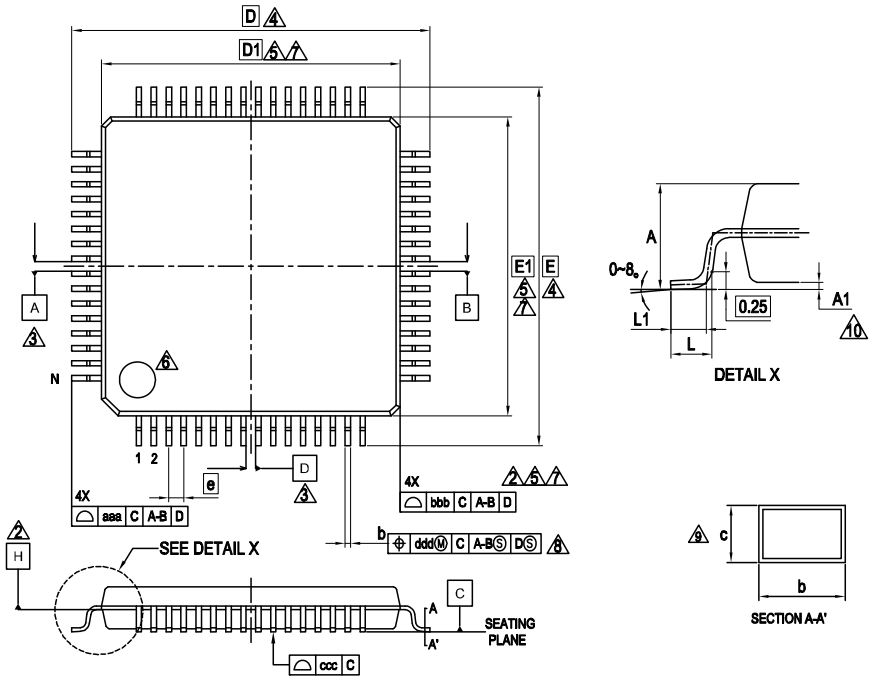
Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Min	Max		
Input pulse width	t_{INH} t_{INL}	ADTG	-	$2t_{CYCP}$*	-	ns	A/D converter trigger input
		FRCKx					Free-run timer input clock
		ICxx					Input capture
		DTTIxX	-	$2t_{CYCP}$*	-	ns	Wave form generator
		INTxx, NMIX	Except Timer mode, Stop mode	$2t_{CYCP}$ + 100*	-	ns	External interrupt NMI
			Timer mode, Stop mode	500	-	ns	

*1: t_{CYCP} indicates the APB bus clock cycle time.
About the APB bus number which the A/D converter, Multi-function Timer, External interrupt are connected to, see "8. Block Diagram" in this datasheet.



Package Type	Package Code
LQFP 64	LQD064

LQD064-02 , 64 Lead Plastic Low Profile Quad Flat Package



PACKAGE	LQD64-02		
SYMBOL	MIN.	NOM.	MAX.
A	—	—	1.70
A1	0.00	—	0.20
b	0.17	0.22	0.27
c	0.09	—	0.20
D	12.00 BSC.		
D1	10.00 BSC.		
e	0.50 BSC		
E	12.00 BSC.		
E1	10.00 BSC.		
L	0.45	0.60	0.75
L1	0.30	0.50	0.70
aaa	—	—	0.20
bbb	—	—	0.10
ccc	—	—	0.08
ddd	—	—	0.08
N	64		

NOTES

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (mm)
2. DATUM PLANE H IS LOCATED AT THE BOTTOM OF THE MOLD PARTING LINE COINCIDENT WITH WHERE THE LEAD EXITS THE BODY.
3. DATUMS A-B AND D TO BE DETERMINED AT DATUM PLANE H.
4. TO BE DETERMINED AT SEATING PLANE C.
5. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25mm PRE SIDE. DIMENSIONS D1 AND E1 INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
6. DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED.
7. REGARDLESS OF THE RELATIVE SIZE OF THE UPPER AND LOWER BODY SECTIONS. DIMENSIONS D1 AND E1 ARE DETERMINED AT THE LARGEST FEATURE OF THE BODY EXCLUSIVE OF MOLD FLASH AND GATE BURRS. BUT INCLUDING ANY MISMATCH BETWEEN THE UPPER AND LOWER SECTIONS OF THE MOLDER BODY.
8. DIMENSION b DOES NOT INCLUDE DAMBER PROTRUSION. THE DAMBAR PROTRUSION (S) SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED b MAXIMUM BY MORE THAN 0.08mm. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE LEAD FOOT.
9. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10mm AND 0.25mm FROM THE LEAD TIP.
10. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.

Rev. A